

SOT281

plastic single-ended package; 5-lead low-profile TO-220

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	TO-220
Package type industry code	TO-220
Package style descriptive code	SIP (single in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	11-6-1997

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10	-	10.5	11	mm
E	package width	9.7	-	10	10.3	mm
A	seated height	4.1	-	4.5	4.5	mm
n ₂	actual quantity of termination	-	-	5	-	



2. Package outline

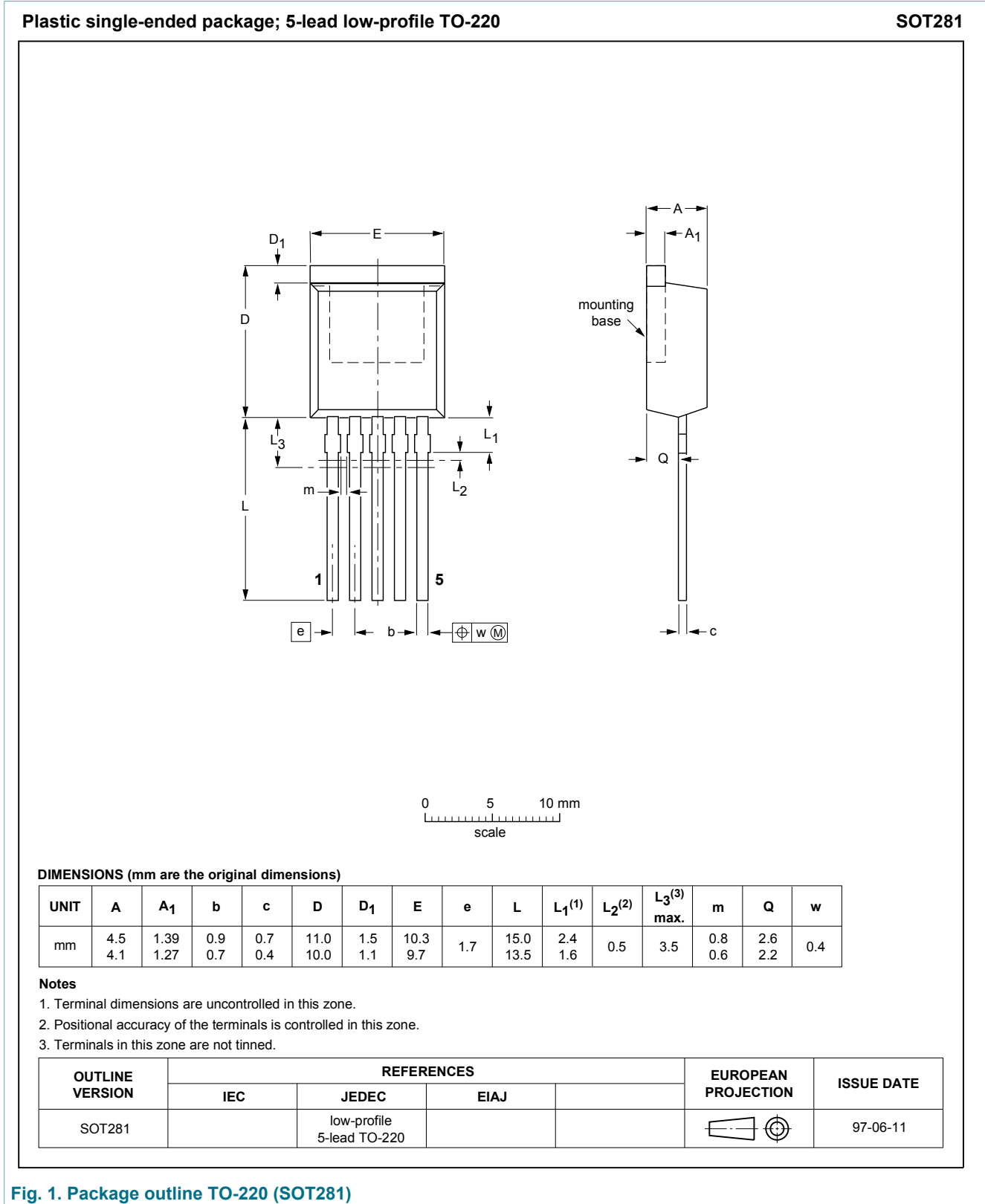


Fig. 1. Package outline TO-220 (SOT281)

3. Legal information

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